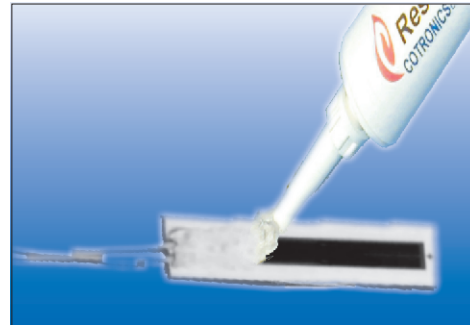


3000°F Resbond™ 989FS

High Purity Alumina Adhesive

Rapid Curing Formulation

- Easy to Use
- One Component
- Free Flowing
- Room Temp. Cures



Users Report: Resbond™ 989FS Bonds Sensors For High Speed, High Temp. Production Applications

Resbond™ 989FS Fast Setting 3000°F, High Purity, Alumina Adhesive,

Now a free flowing formulation that is ideal for use in automatic dispensing equipment.

One component. Just apply and let dry.

Can be dispensed automatically for high speed, high volume applications.

Resbond 989FS cures at room temperature or in 5 minutes at 200°F.

Offers high bond strength and excellent electrical, moisture, chemical and solvent resistance.

Has excellent adhesion to metals, ceramics, graphite or glass.

Applications include production bonding, adhering thermocouples, heat sensors, and critical electronic components for use to 3000°F.

Resbond 989FS is the Ideal Choice For Any High Temperature Electrical Application Requiring Excellent Electrical, Chemical, Moisture and Corrosion Resistance.

Physical Properties

Max. Use Temp.	3000 °F
Base	Al ₂ O ₃
Compressive Strength	3,500 psi
Flexural Strength	1,250 psi
Dielectric Strength	200 volts/mil
Specific Heat	0.24 BTU / # °F
Volume Resistance	10 ⁸
Thermal	
Conductivity	15.0 BTU in/hr. °F ft. ²
Expansion	4.5 x 10 ⁻⁶ /°F
Color	White
Consistency	Creamy Paint

Availability

Cat #	Description
989FS - 1	High Purity Alumina Adhesive
989FS - 2	High Purity Alumina Adhesive
989FS - 3	High Purity Alumina Adhesive

Distributed By:



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